

Title (en)

Wire guide monitoring device and method for monitoring a wire guide

Title (de)

Drahtführungsüberwachungsvorrichtung und Verfahren zur Überwachung eines Führungsdrahts

Title (fr)

Dispositif de surveillance de guide de fil et procédé de surveillance d'un guide de fil

Publication

EP 2933049 A1 20151021 (EN)

Application

EP 14165254 A 20140417

Priority

EP 14165254 A 20140417

Abstract (en)

A wire guide monitoring device for a wire saw, a wire saw including the wire guide monitoring device and a method for monitoring the wire guide is described. The wire guide monitoring device (500) includes an optical sensor device (510) for measuring surface characteristics of a wire guide (200), and a coupling element (530) for coupling the wire guide monitoring device to a kinematic mechanism structure (350) of an ingot feeding system (300) of the wire saw.

IPC 8 full level

B23D 59/00 (2006.01); **B28D 5/04** (2006.01)

CPC (source: EP)

B28D 5/0064 (2013.01); **B28D 5/045** (2013.01)

Citation (search report)

- [Y] JP H1015805 A 19980120 - TOKYO SEIMITSU CO LTD
- [Y] DE 10220640 A1 20021219 - WACKER SILTRONIC HALBLEITERMAT [DE]
- [A] WO 2011070386 A1 20110616 - APPLIED MATERIALS INC [US], et al
- [A] US 5913305 A 19990622 - HAUSER CHARLES [CH]

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA ME

DOCDB simple family (publication)

EP 2933049 A1 20151021; CN 105014804 A 20151104; CN 204036679 U 20141224

DOCDB simple family (application)

EP 14165254 A 20140417; CN 201410315096 A 20140703; CN 201420366308 U 20140703